PCN Number: 20201106000.1 PCN Date: Nov 6, 2020											
Title: Qualification of Carsem Suzhou as an additional Assembly site for Select Devices											
Customer Contact: PCN Manager Dept: Quality Services											
Proposed 1 st Ship Date: Feb 6, 2021 Estimated Sample Date pro						•					
Availability: sample request											
Change Type:											
Assembly Site		Design Wafer Bump Sit					rial				
Assembly Proces		Data Sheet Part number change				=	Wafer Bump Material Wafer Bump Process				
Mechanical Spec	n	Test Site				-		Fab S		C33	
Packing/Shippin		Test Process				_			Materia	als	
								Proces			
			PC	N Det	ails						
Description of Cha	nge:										
Texas Instruments is pleased to announce the qualification Carsem Suzhou as an additional assembly site for the list of devices below. Current assembly site and Material differences are as follows:											
			U	ТАС				CA	RZ		
Lead finish	Lond finish			NiPdAu			NiPdAuAg				
Leau IIIIsi	Lead finish			(Non-rough)			(Single Side Top Roughened)				
Wire type			Au			Cu					
Mount Cor	ount Compound			PZ0035			443156				
Reason for Change	:										
Continuity of Supply											
1) To align with world technology trends and use wiring with enhanced mechanical and											
electrical properties											
 Maximize flexibility within our Assembly/Test production sites. 											
3) Cu is easier to obtain and stock											
Anticipated impact	: on Fo	rm, Fit,	Functio	on, Qua	lity or Reli	abili	ity (p	osi	tive	/ neg	ative):
None											
Anticipated impact	t on Ma	aterial D	Declarat	ion							
No Impact to the Material Declar	Dect to the Il DeclarationMaterial Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised 					e ed					
Changes to produc	t ident	ificatio	n result	ing fro	m this PCN	l:					
Assembly Site			v Site Origin 22L)		Assembly Country Code		le (23L)			Assembly City	
UTAC		NSE		THA				Bangkok			
Carsem	Carsem CSZ			CHN				Jiangsu			
Sample product shipping label (not actual product label)											



Qualification Data Approve Date 15-Oct-2020

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: AMC7834IRTQR	QBS Product Reference: <u>AMC7834BIRTQ</u>	QBS Product/Package Reference: <u>AMC7834IRTQR</u>	QBS Process Reference: <u>ADS1232IPW</u>	QBS Process Reference: <u>ADS1259BIPW</u>	QBS Process Reference: <u>AMC7812SPAP</u>
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	1/77/0	1/77/0	3/231/0
HBM	ESD - HBM	1000 V	-	-		-	-	3/9/0
HBM	ESD - HBM	2000 V	-	-	-	1/3/0	1/3/0	-
HBM	ESD - HBM	750 V	-	-	1/3/0	-	-	-
CDM	ESD - CDM	250 V	-	1/3/0	1/3/0	-	-	-
CDM	ESD - CDM	500 V	-	-	-	1/3/0	1/3/0	3/9/0
LU	Latch-up	Per JESD78	-	1/6/0	1/6/0	1/6/0	1/6/0	3/18/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	3/231/0	-	-	-	-	
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/135/0	1/77/0	1/77/0	3/231/0
TC	Temperature Cycle, - 65/150C	500 Cycles	3/231/0	-	3/231/0	1/77/0	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	3/231/0	-	-	-

- QBS: Qual By Similarity

- Qual Device AMC7834IRTQR is qualified at LEVEL3-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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